



N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY

V _{DSS}	I _D	R _{DS(ON)} (mΩ) Max
40V	11A	11.5 @ V _{GS} =10V
		15 @ V _{GS} =4.5V

FEATURES

- Super high dense cell design for low R_{DS(ON)}.
- Rugged and reliable.
- Surface Mount Package.



ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise noted)

Symbol	Parameter	Limit	Units
V _{DS}	Drain-Source Voltage	40	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current-Continuous ^a	T _C =25°C	11
		T _C =70°C	8.8
I _{DM}	-Pulsed ^b	44	A
E _{AS}	Single Pulse Avalanche Energy ^d	110	mJ
P _D	Maximum Power Dissipation ^a	T _C =25°C	3
		T _C =70°C	1.9
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 to 150	°C

THERMAL CHARACTERISTICS

Symbol	Parameter	Limit	Units
R _{θJA}	Thermal Resistance, Junction-to-Ambient ^a	42	°C/W

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ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	40			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =32V, V _{GS} =0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V, V _{DS} =0V			±100	nA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	1.5	3	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =11A		9	11.5	m ohm
		V _{GS} =4.5V, I _D =10A		11	15	m ohm
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =11A		40		S
DYNAMIC CHARACTERISTICS °						
C _{ISS}	Input Capacitance	V _{DS} =20V, V _{GS} =0V f=1.0MHz		1160		pF
C _{OSS}	Output Capacitance			218		pF
C _{RSS}	Reverse Transfer Capacitance			140		pF
SWITCHING CHARACTERISTICS °						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =20V I _D =1A V _{GS} =10V R _{GEN} = 6 ohm		18.2		ns
t _r	Rise Time			26		ns
t _{D(OFF)}	Turn-Off Delay Time			65		ns
t _f	Fall Time			16		ns
Q _g	Total Gate Charge	V _{DS} =20V, I _D =11A, V _{GS} =10V		22		nC
		V _{DS} =20V, I _D =11A, V _{GS} =4.5V		11.2		nC
Q _{gs}	Gate-Source Charge	V _{DS} =20V, I _D =11A,		2.5		nC
Q _{gd}	Gate-Drain Charge	V _{GS} =10V		5.4		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
I _S	Maximum Continuous Drain-Source Diode Forward Current				2.5	A
V _{SD}	Diode Forward Voltage ^b	V _{GS} =0V, I _S =2.5A		0.76	1.2	V
Notes						
<p>a. Surface Mounted on FR4 Board, t ≤ 10sec.</p> <p>b. Pulse Test: Pulse Width ≤ 300us, Duty Cycle ≤ 2%.</p> <p>c. Guaranteed by design, not subject to production testing.</p> <p>d. Starting T_J=25°C, L=0.5mH, V_{DD} = 20V. (See Figure 13)</p>						

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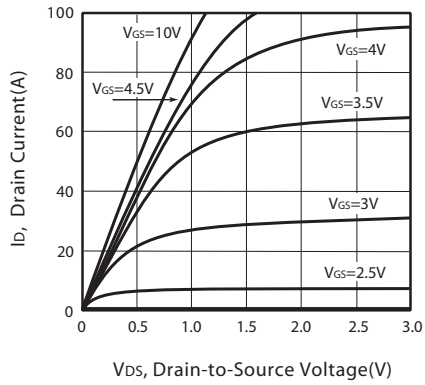


Figure 1. Output Characteristics

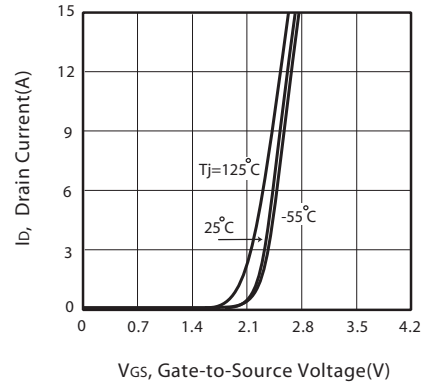


Figure 2. Transfer Characteristics

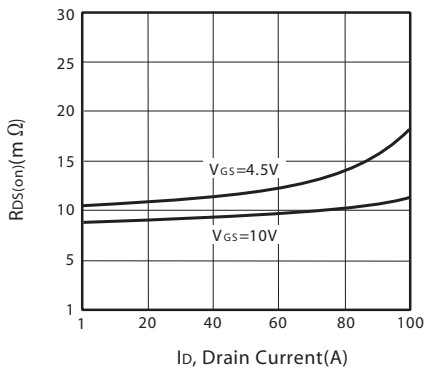


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

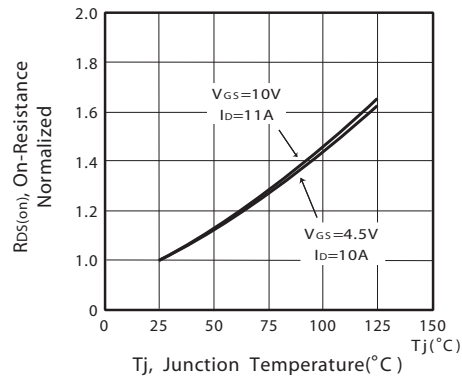


Figure 4. On-Resistance Variation with Drain Current and Temperature

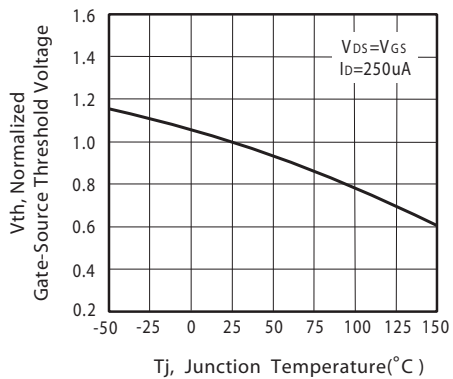


Figure 5. Gate Threshold Variation with Temperature

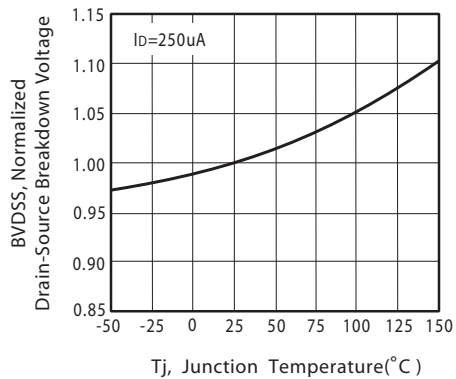


Figure 6. Breakdown Voltage Variation with Temperature

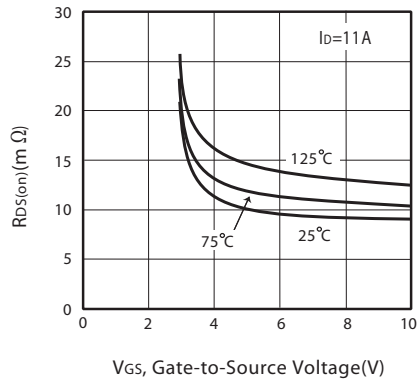


Figure 7. On-Resistance vs. Gate-Source Voltage

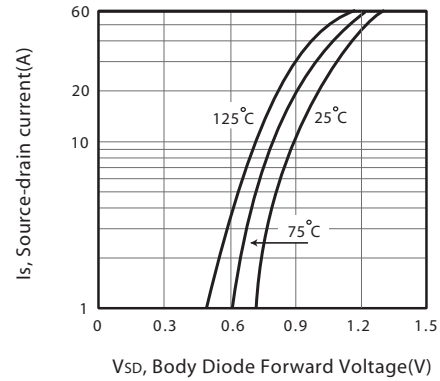


Figure 8. Body Diode Forward Voltage Variation with Source Current

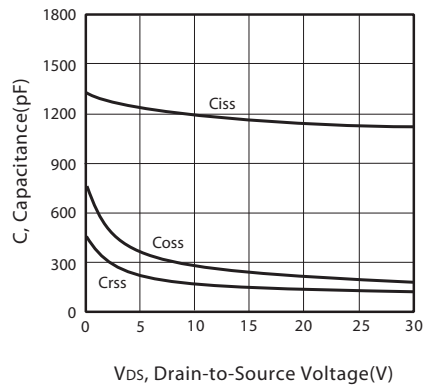


Figure 9. Capacitance

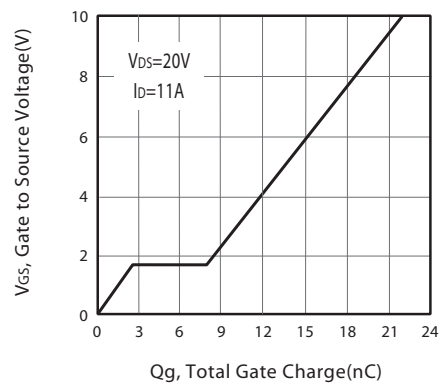


Figure 10. Gate Charge

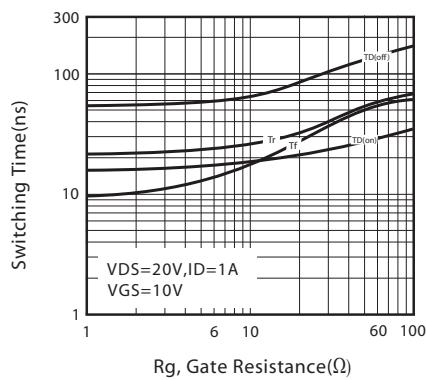


Figure 11. switching characteristics

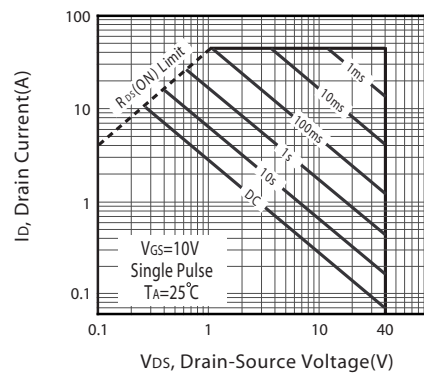
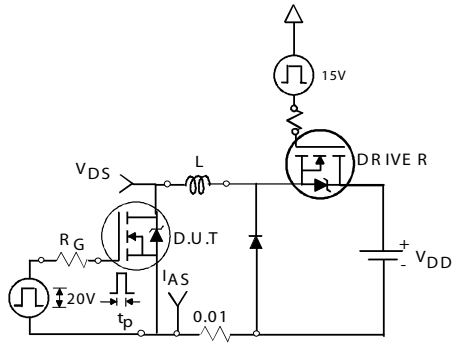
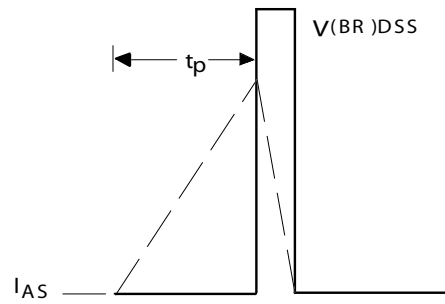


Figure 12. Maximum Safe Operating Area



Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

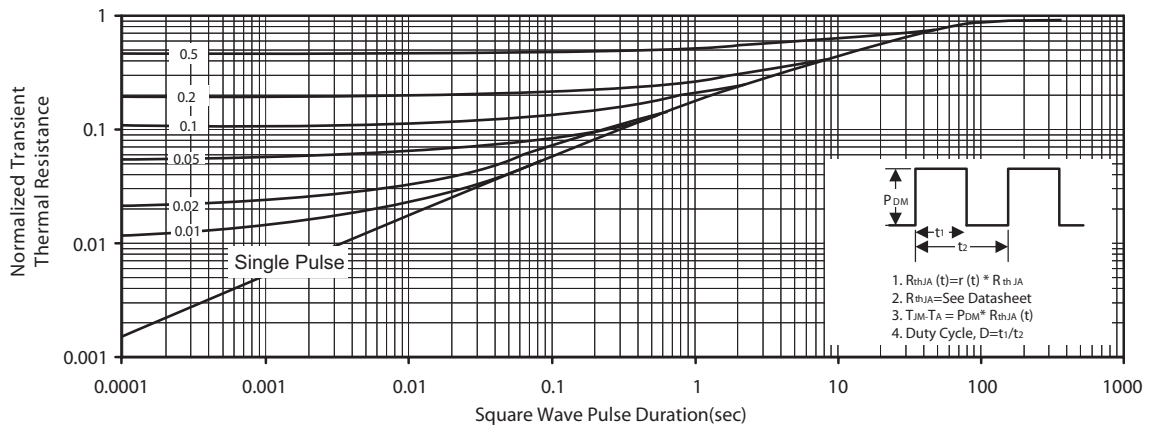
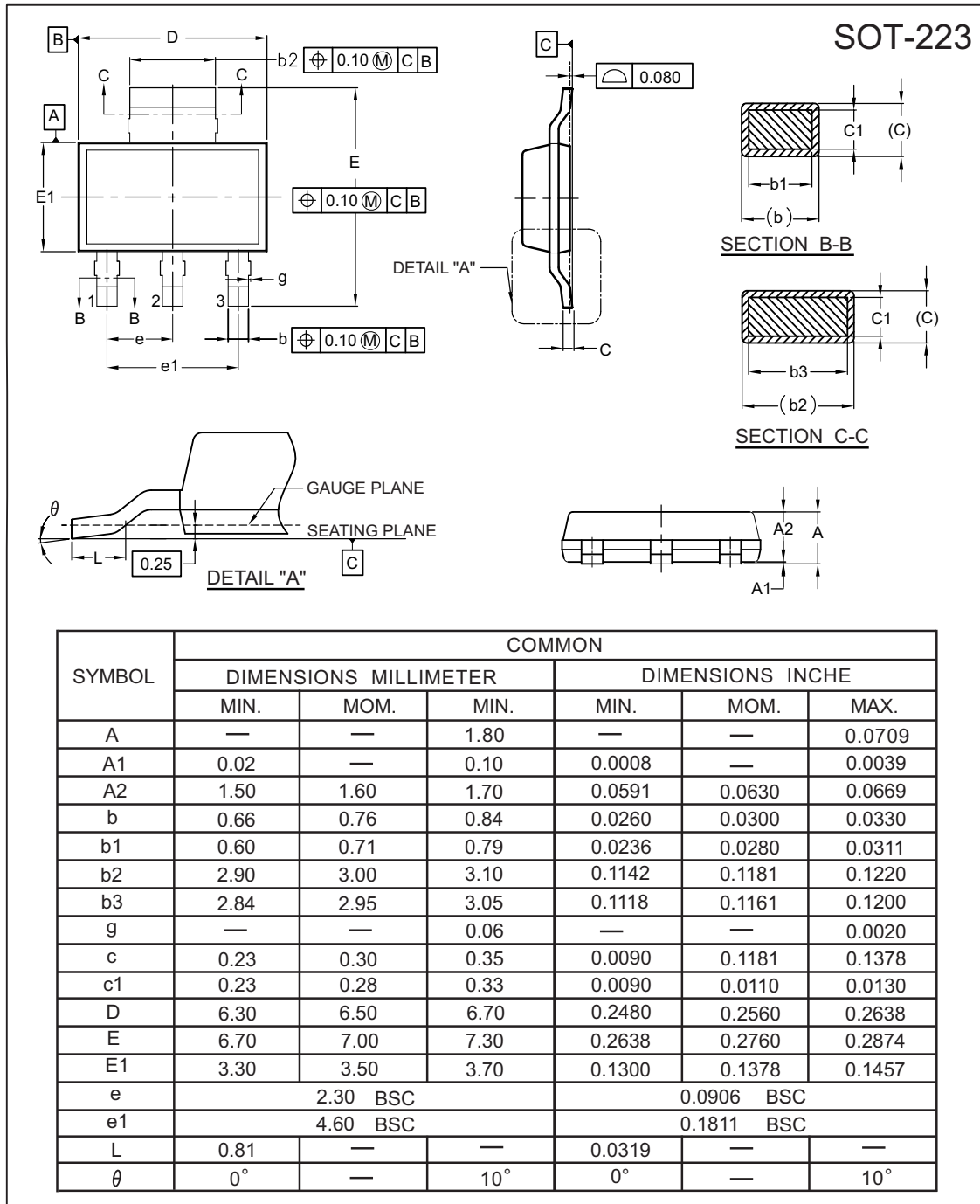


Figure 14. Normalized Thermal Transient Impedance Curve

STT432S

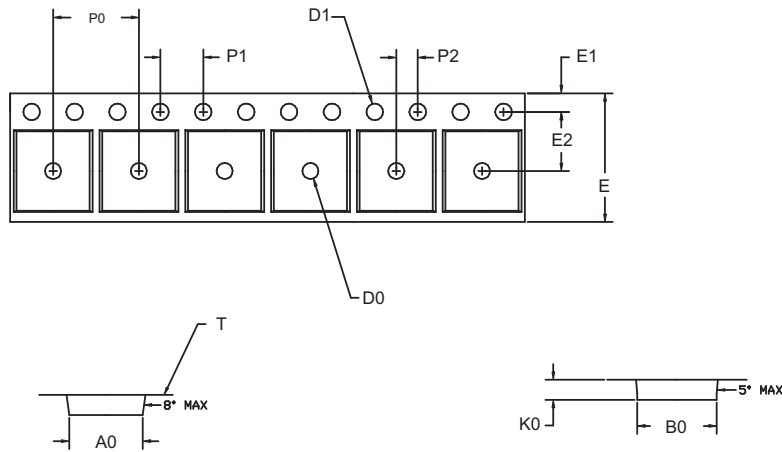
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SOT-223 Tape and Reel Data

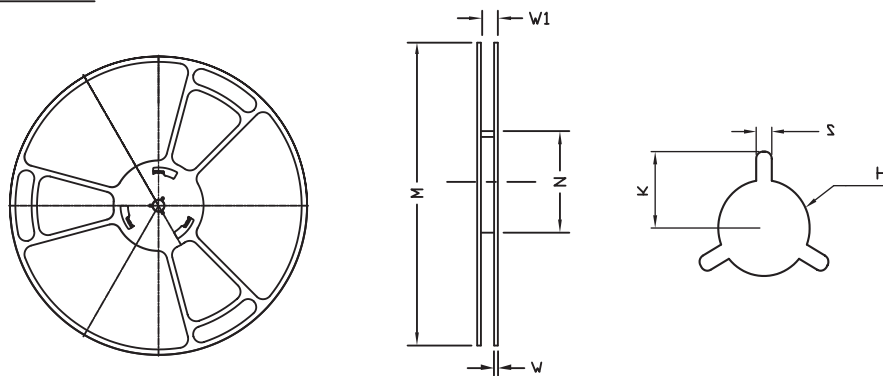
SOT-223 Carrier Tape



unit:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
---	6.83 ±0.1	7.42 ±0.1	1.88 ±0.1	1.50 + 0.25	1.60 + 0.1	12.0 + 0.3 - 0.1	1.75 ±0.1	5.50 ±0.5	8.0 ±0.1	4.00 ±0.1	2.00 ±0.05	0.292 ±0.02

SOT-223 Reel



UNIT:mm

REEL SIZE	M	N	W	W1	H	K	S	G	R	V
φ 330 ± 0.5	---	φ 97.0 ± 1.0	2.2	13.0 + 1.5	φ 13.0 + 0.5 - 0.2	10.6	2.0 ±0.5	---	---	---